

EL979950145



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2827
Examiner David A. Zarneke
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

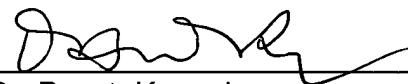
References –See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: 1-5-04

By: 
D. Brent Kenady
Reg. No. 40,045

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO. MI22-1572		SERIAL NO. 09/756,971	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Salman Akram			
				FILING DATE January 9, 2001		GROUP 2827	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	6,326,687 B1	12/04/01	Corisis			
	AB	6,518,098 B2	02/11/03	Corisis			
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes
	AM						No
	AN						
	AO						
	AP						
	AQ						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR		"Thermal Conductivity of Metals (at 100°K)." retrieved on 2003, July 01.				
			Retrieved from the Internet: http://www.reade.com/Particle_Briefings/thermal_con_metals.html . 7 pages.				
	AS						
	AT						
EXAMINER				DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							